NOTES:
1. LEAK TEST: 80 PSI, NO BUBBLES 3 MINUTES MINIMUM.
2. HYPOT 630 VDC 500 MΩ MINIMUM 0.01 SECOND MINIMUM
   WIRE TO WIRE.
3. ALL TESTS ARE PERFORMED AT ROOM TEMPERATURE.
4. ALL PARTS MUST PASS ALL TESTS.
5. ITEMS 4 & 5 TO BE 2 TWISTED PAIRS, ONE WHITE WIRE TWISTED WITH
   ONE BLUE WIRE @ APPROXIMATELY 2 TWISTS PER INCH BOTH SIDES.
6. WIRE TO WIRE.
7. NO BUBBLES ARE ALLOWED ON O-RING SEALING SURFACES, Voids
   SMALLER THAN ±.005 [.13] MAXIMUM.
8. NO BUBBLES ARE ALLOWED ON O-RING SEALING SURFACES, Voids
   SMALLER THAN ±.005 [.13] MAXIMUM.
9. REFRAP PARTS ARE DATED ON PARTING LINE ±.005 [.13] MAXIMUM.
10. REFRAP-RATING TEMPERATURE RANGE -20°C TO 125°C.
11. DIMENSIONS ARE IN INCHES [millimeters].